

Title (en)  
SEMICONDUCTOR PACKAGE WITH TRANSPARENT LID

Title (de)  
HALBLEITERKAPSELUNG MIT TRANSPARENTEM DECKEL

Title (fr)  
BOITIER A SEMI-CONDUCTEUR PRESENTANT UN COUVERCLE TRANSPARENT

Publication  
**EP 1751792 A1 20070214 (EN)**

Application  
**EP 05748145 A 20050606**

Priority  
• IB 2005001590 W 20050606  
• GB 0412436 A 20040604

Abstract (en)  
[origin: WO2005119756A1] A transparent wafer (101), typically a glass wafer, is placed over a silicon wafer (100) having an integrated circuit with one or more optically active elements (106) provided thereon. The transparent wafer (101) is securely sealed to the silicon wafer (100) by a pattern of glass frit material (104) applied to one or both wafers (100, 101). The glass frit pattern (104) is screen printed on to the appropriate wafer (100, 101) and is arranged so as to surround the or each optically active element or elements (106) of each integrated circuit. The two wafers (100, 101) are aligned and brought together. The wafers (100, 101) are then raised in temperature to cause the glass frit material (105) to reflow and seal the wafers together. In this manner, the glass frit (105) seals the gap between the two wafers (100, 101).

IPC 8 full level  
**H01L 21/56** (2006.01); **H01L 21/78** (2006.01); **H01L 21/784** (2006.01); **H01L 33/00** (2006.01); **G02B 6/42** (2006.01)

CPC (source: EP)  
**H01L 27/14618** (2013.01); **G02B 6/4204** (2013.01); **H01L 2224/48247** (2013.01); **H01L 2924/10253** (2013.01)

Citation (search report)  
See references of WO 2005119756A1

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**WO 2005119756 A1 20051215**; EP 1751792 A1 20070214; GB 0412436 D0 20040707

DOCDB simple family (application)  
**IB 2005001590 W 20050606**; EP 05748145 A 20050606; GB 0412436 A 20040604